

05-11-1999

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To the Honorable Commissioner of Patents and Trademark

101035462

ments or copy thereof.

1. Name of conveying party(ies):

Brian A. Vaartstra

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Nature of conveyance:

☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date: April 21, 1999

2. Name and address of receiving party(ies):

Name: Micron Technology, Inc.

Street Address: 8000 South Federal Way

City: Boise State: ID ZIP: 83707

Additional name(s) & address(es) attached? ☐ Yes ☒ No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: April 21, 1999

A. Patent Application No(s).

B. Patent No(s).

09/300017

Title: **METHODS FOR FORMING CONFORMAL IRIIDIUM LAYERS ON SUBSTRATES**

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ann M. Mueting  
Address: MUETING, RAASCH & GEBHARDT, P.A.  
P.O. Box 581415  
Minneapolis, MN 55458-1415

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR §3.41): \$ 40.00

☒ Enclosed  
☐ Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to Deposit account number: 13-4895

05/10/1999 JSHABAZZ 00000109 09300017

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Ann M. Mueting/Reg. No.33,977  
Name of Person Signing

Signature

April 27, 1999  
Date

Total number of pages including cover sheet, attachments, and document(s): 2

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents and Trademarks  
Box Assignments  
Washington, D.C. 20231

## ASSIGNMENT

Whereas I, Brian A. Vaartstra, with residence and citizenship as indicated below; have made an invention in

**METHODS FOR FORMING CONFORMAL IRIIDIUM  
LAYERS ON SUBSTRATES**

Filed: Herewith

Serial No.: Unassigned

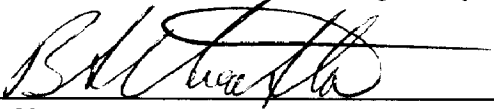
and executed an application for Letters Patent of the United States of America based thereon;

Now, therefore, for good and valuable consideration, receipt of which is acknowledged, I have agreed to assign and transfer and do hereby assign and transfer unto Micron Technology, Inc. ("Company"), a corporation of Boise, Idaho, having its principal office at 8000 South Federal Way, Boise, Idaho 83707, its successors and assigns, the entire right, title, and interest in and to said invention and application, and in and to any division or continuation (in whole or in part) of said application, and in and to any and all improvements in said invention made by me or made jointly with others (provided any such improvement is made during, or within one year after the termination of, the employment by the Company of whichever of us, solely or jointly with one or more others, has made the same), and in and to any and all Letters Patent, reexaminations, reissues, or extensions thereof, of the United States of America and countries foreign thereto (including the right to apply for Letters Patent, Utility Models, or Inventors' Certificates in foreign countries in its own name and to claim any priority rights for such foreign applications to which such applications are entitled under international conventions, treaties, or otherwise), which have been or may be granted thereon or on any divisional, continuation (in whole or in part), renewal, reexamination, reissue, or other or further application based in whole or in part upon said invention or improvements thereon, to be held and enjoyed as fully and exclusively as they would have been by me had this assignment and transfer not been made;

I do further agree for myself and for my heirs, executors, and administrators, to execute and deliver without further consideration any further applications, assignments, and documents, and to perform such other acts as I lawfully may, that may be deemed necessary by the Company, its successors, assigns, and nominees, fully to secure its right, title, and interest as aforesaid and to obtain or maintain Letters Patent, Utility Models, or Inventors' Certificates in any and all countries;

And I do hereby authorize and request the Commissioner of Patents to issue any and all Letters Patent which may be granted upon any of said applications, to Micron Technology, Inc. as the assignee of the entire right, title, and interest therein.

In witness whereof, I have hereunto signed my name on the day and year set forth below.



21 Apr 99

Name: Brian A. Vaartstra

Date

Address: 3417 Braden Lane, Nampa, Idaho 83686

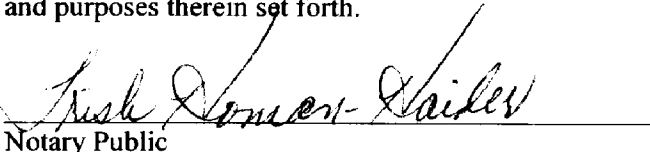
Citizenship: Canada

STATE OF Idaho )

) ss.

COUNTY OF Ada )

On this 21st day of April 19 99 before me personally appeared Brian A. Vaartstra to me known to be the person described in and who executed the foregoing instrument, and he/she executed the same for the uses and purposes therein set forth.

  
Notary Public

My Commission Expires 3-26-03

